

Material Composition Data

Product: GTXO-83

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GTXO-83 - 2.4V ~ 5.5V SM (VC)TCXO Clipped Sine

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Au wire	Gold	Au	7440-57-5	1.220	100.00
Ceramic base	Alumina	Al ₂ O ₃	1344-28-1	35.450	72.10
	Chromium Dioxide	Cr ₂ O ₃ (Non hex)	1308-38-9	0.180	0.37
	Gold plating	Au	7440-57-5	0.967	1.97
	Kovar Ring	Fe	7439-89-6	3.480	7.08
	Kovar Ring	Ni	7440-02-0	1.870	3.80
	Kovar Ring	Co	7440-48-4	1.102	2.24
	Molybdenum	Mo	7439-98-7	0.240	0.49
	Molybdenum	Mo	7439-98-7	0.090	0.18
	Nickel	Ni	7440-02-0	1.940	3.95
	Silica	SiO ₂	14808-60-7	1.130	2.30
Tungsten	W	7440-33-7	2.720	5.53	
Conductive adhesive	Silicon resin	Si	7440-21-3	0.004	10.53
	Silver powder	Ag	7440-22-4	0.034	89.47
Crystal blank	Synthetic quartz	SiO ₂	14808-60-7	2.020	100.00
Electrode	Gold	Au	7440-57-5	0.040	100.00
IC	Aluminium	Al	7429-90-5	0.360	14.60
	Pad	Cu	7440-50-8	0.040	1.62
	Silicon Chip	Si	7440-21-3	2.065	83.77
Metal Cap	Ag Filler	Ag	7440-22-4	0.290	3.82
	Copper	Cu	7440-50-8	0.110	1.45
	Kovar	Fe	7439-89-6	3.670	48.29
	Kovar	Ni	7440-02-0	1.970	25.92
	Kovar	Co	7440-48-4	1.160	15.26
	Nickel	Ni	7440-02-0	0.400	5.26
Total Mass:				62.552 mg	

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